ON Semiconductor

FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #20383

Generic Copy

Issue Date: 19-Feb-2014

TITLE: Copper Wire for SOIC-8 MCM Package

PROPOSED FIRST SHIP DATE: 19-May-2014

AFFECTED CHANGE CATEGORY(S): ON Semiconductor Manufacturing Assembly

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or Rob Prestoza <Rob.Prestoza@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office or Tomas Vajter <Tomas.Vajter@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

Referencing to the General Announcement # GA 16200: Conversion of Gold Wire to Copper Wire in ON Semiconductor’s Assembly Facilities, ON Semiconductor is notifying customers of its use with either Gold or Copper Wire on their SOIC-8 MCM type packaged products. The affected SOIC-8 MCM products are represented by this Process Change Notice.

Reliability Qualification and Full Electrical Characterization over temperatures have been performed.

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RELIABILITY DATA SUMMARY:

Reliability Test Results: NCP3170ADR2G

Test		Conditions	Results
HTOL	High Temp Op Life	TA=125C; 2016hrs	0/240
HTSL	High Temp Storage Life	TA=175C; 1008hrs	0/240
HTSLx	High Temp Storage Life Special	TA=150C; 2520hrs	0/240
RSH	Resistance to Solder Heat	TA=245C;	0/90
PC	Moisture Preconditioning	MSL1 @ 260C	0/240
UHAST-PC	Pre-con Unbiased HAST	TA=130C; RH=85%; PSIG=18.8; 192hrs	0/240
TC-PC	Pre-con Temp Cycle	-65 to +150C; 2000cycs	0/240
HAST-PC	Pre-con HAST	TA=130C; RH=85%; PSIG=18.8; bias; 192hrs	0/240

ELECTRICAL CHARACTERISTIC SUMMARY:

There is no change in the Electrical Parametric performance. Characterization data is available upon request.

CHANGED PART IDENTIFICATION:

There will be no physical change with the products assembled with Copper Wire as compared to Gold Wire.

List of affected General Parts:

NCP3170ADR2G
NCP3170BDR2G